United Adhesives, Inc.
Asia +86 (139) 5605 4600 North America & Europe +1 (224) 436 0077 Sales@UnitedAdhesives.com
www.UnitedAdhesives.com

ET1645NS

High Thermally Conductive Epoxy Adhesive

Typical Properties			
Property	**Unit**	**Value**	**Test Method**
Color / Component A		Grey	Visual
Color / Component B		Off White	Visual
Mixing Ratio A :B	In Weight	1 : 1	
Density (mixed)	Gram /cc	2.5	ASTM D792
Viscosity at 25°C (mixed)	cP.s	80,000	ASTM D2196
Thixotropic Index	1 s^{-1} / 10 $^{-1}$	3.5	ASTM D2196
Property as Cured			
Color		Light Grey	Visual
Hardness	Shore D	70	ASTM D2240
Thermal Conductivity	W/m-K	1.5	ASTM D5470
Heat Capacity at 25°C	J/g-K	1.0	ASTM D1269
Dielectric Strength	Volt/mil AC	> 550	ASTM D149
Volume Resistivity	Ohm-cm	> 10E+13	ASTM D257
Coefficient of Thermal Expansion	ppm/C	79 (@ > Tg) 25 (@ < Tg)	IPC-TM-650
Adhesion (Al/Al lap shear)	Psi	> 1000	ASTM D1002
Tg	℃	150	DMA
Temperature Usage	℃	-80 to 180	TGA
Cure Profile			
Cure at 125°C	hr	2	DSC
Cure at 150°C	Min	45	DSC
Pot Life at 25°C	hr	> 8	Viscosity double

These figures are only intended as a guide and should not be used in preparing specifications.

Characteristics

ET1645NS is a non-slumping version of epoxy-based high thermally conductive structural bonding adhesive for electronic applications. It is two components, 1:1 in weight mixing ratio, thixotropic (non-slumping), heat-curing system that cures elevated temperature to provide strong bonding to metals such as aluminum, copper, and FR4 based printed circuit board with excellent thermal conductivity. The cured material also has very low CTE for better thermal cycle performances.

Special Features and Benefits

- High thermal conductivity
- High temperature stability
- Low CTE for stress compliance
- Low bleeding, low volatile
- Low ionic content
- ET1645NS can have pre-added 7 mil glass beads for thickness control if required

Typical Applications

- Aerospace electronics
- Automotive electronics
- Semiconductor and Telecommunications
- Between high heat power device and heat sink
- Thermally conductive structural bonding
- Thermally conductive vibration

Processing Instruction

For the package in a container (not in a cartridge), to ensure homogeneity of the material, the components must be stirred thoroughly before they are mixed, removed or processed in order to uniformly disperse any fillers that might have settled during storage.

We recommend running preliminary tests to optimize conditions for the particular application. Comprehensive processing instructions can be obtained by contacting directly to United Adhesives Inc.

Storage

ET1645NS has a shelf life of at least 6 months when stored at ambient in the originally sealed container. The 'Best use before end' date of each batch appears on the product label. Storage beyond the date specified on the label does not necessarily mean that the product is no longer usable. In this case however, the properties required for the intended use must be checked for quality assurance reasons.

Safety information

General hygiene regulations should be observed. Comprehensive instructions are given in the corresponding Material Safety Data Sheets. They are available on request from United Adhesives Inc.